



THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re the Application of

Inventors: Eiko SEIDEL, et al.

Appln. No.: 10/567,825

Filed: February 10, 2006

For: TIME MONITORING OF PACKET RETRANSMISSIONS DURING
SOFT HANDOVER

INFORMATION DISCLOSURE STATEMENT

Assistant Commissioner of Patents
Washington, DC 20231

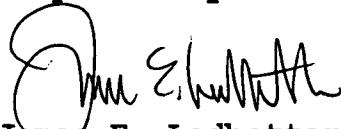
Dear Sir:

Pursuant to Rules 56 and 99, Applicants hereby call the attention of the Patent Office to the documents listed on the attached Form PTO 1449. U.S. Application No. 2002/019965 issued as U.S. Patent No. 6,557,134.

Applicants present this art so that the Patent Office may, in the first instance, determine any relevancy thereof to the presently claimed invention, see Beckman Instruments, Inc. v. Chemtronics, Inc., 439 F.2d 1369, 1380, 165 USPQ 355, 364 (5th Cir. 1970). Also see Patent Office Rules 104 and 106. Applicants respectfully request that this art be expressly considered during the prosecution of this application and made of record herein and

appear among the "References Cited" on any patent to issue herefrom.

Respectfully submitted,



James E. Ledbetter
Registration No. 28,732

Date: June 21, 2006

JEL/ejw

ATTORNEY DOCKET NO. L7725.06102

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FORM PTO-1449 U.S. Department of Commerce
(Rev. 4/92) Patent and Trademark Office

ATTY. DOCKET NO.

SERIAL NO.

L7016.06102

09/978,679

INFORMATION DISCLOSURE
STATEMENT BY APPLICANT

JUN 21 2006

(Use several sheets if necessary)

APPLICANT

Eiko SEIDEL, et al.

FILING DATE

February 10, 2006

GROUP

Unassigned

U.S. PATENT DOCUMENTS

EXAMINER INITIAL		DOCUMENT NUMBER								DATE	NAME	CLASS	SUBCLASS	FILING DATE IF APPROPRIATE	
		6	5	5	7	1	3	4							
/EA/		6	5	5	0	7	6	9		04/2003	Bims et al.				
/EA/		6	8	5	0	7	6	9		02/2005	Grob et al.				
/EA/	2004	0	1	1	6	1	4	3		06/2004	Love et al.				

FOREIGN PATENT DOCUMENTS

		DOCUMENT NUMBER								DATE	COUNTRY	CLASS	SUBCLASS	TRANSLATION	
		0	2	3	7	8	7	2							
/EA/		0	2	3	7	8	7	2		05/2002	WO				YES NO

OTHER DOCUMENTS (Including Author, Title, Date, Pertinent Pages, Etc.)

/EA/	"UTRAN Overall Description," 3GPP TS 25.401 v6.1.0, Release 6, Technical Specification, 3 rd Generation Partnership Project, Technical Specification Group Radio Access Network, www.3gpp.org, pages 1-44, Jun. 2003.
/EA/	"Feasibility Study on the Evolution of UTRAN Architecture," 3GPP TR 25.897v0.2.1, Release 6, Technical Report, 3 rd Generation Partnership Project, Technical Specification Group Radio Access Network, www.3gpp.org, pages 1-16, Jun. 2006.
/EA/	"Proposed Architecture for UTRAN Evolution," 3GPP TSG-RAN WG3 Meeting #36, Tdoc R3-030678, Siemens, 3 pages total, May 19-23, 2003.
/EA/	"Further Clarifications on the Presented Evolved Architecture," 3GPP TSG-RAN WG3 Meeting #36, R3030688, Nokia, 4 pages total, Apr. 7-11, 2003.
/EA/	"Feasibility Study for Enhanced Uplink for UTRA FDD," 3GPP TR 25.896 v6.0.0, Release 6, Technical Report, 3 rd Generation Partnership Project, Technical Specification Group Radio Access Network, www.3gpp.org, pages 1-179, Mar. 2004.
/EA/	"HARQ Structure," 3GPP TSG-RAN WG1 #31 Meeting, Tdoc R1-030247, Samsung Electronics, 3 pages total, Feb. 18-21, 2003.
/EA/	"Requirements for Support of Radio Resource Management (FDD)," Release 6, 3GPP TS 25.133v6.2.0, Technical Specification, 3 rd Generation Partnership Project, Technical Specification Group Radio Access Network, www.3gpp.org, pages 1-162, Jun. 2003.
/EA/	"Radio Resource Control (RRC) Protocol Specification," Release 5, 3GPP TS 25.331 v5.5.0, Technical Specification, 3 rd Generation Partnership Project, (FDD)Technical Specification Group Radio Access Network, www.3gpp.org, pages 1-994, Jun. 2003.
/EA/	International Search Report dated May 17, 2005 and Written Opinion of the International Searching Authority.

EXAMINER

/Esaw Abraham/

DATE CONSIDERED

10/14/2008

EXAMINER: Initial if citation is considered, draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.